



100% Material Declaration Data Sheet for Spartan®-6 FGG484 Package

PK414 (v1.1) Nov 28, 2014

Average Weight: 2.300 g

Component	Substance Description	CAS Number or Description	% of Component	Use in Product	Component Weight/ Substance Weight (in grams)	Component % of Total
Silicon Die					0.090946	3.954%
	Silicon	7440-21-3	100.00		0.090946	
Gold Wire					0.010484	0.456%
	Gold	7440-57-5	99.048		0.010384	
	Palladium	7440-05-3	0.950		0.000100	
	Calcium	7440-70-2	0.002		0.000000	
Die Attach Adhesive					0.016016	0.696%
	Silver	7440-22-4	77.50		0.012412	
	Bismaleimide monomer	Trade Secret	15.00		0.002402	
	Acrylate monomer	Trade Secret	7.50		0.001201	
Substrate					1.367969	59.477%
	Copper	7440-50-8	28.69		0.392508	
	Nickel	7440-02-0	5.68		0.077630	
	Gold	7440-57-5	0.67		0.009225	
	BT (core)	21645-51-2 7440-50-8 Epoxy resin	56.69		0.775444	
	Solder Mask	14807-96-6 7727-43-7 7631-86-9 34590-94-8 85954-11-6	8.27		0.113162	
Mold Compound					0.810542	35.241%
	Solid epoxy resin	Trade Secret	5.000		0.040527	
	Phenol resin	Trade Secret	5.000		0.040527	
	Fused Silica	60676-86-0	84.450		0.684502	
	Metal hydroxide	Trade Secret	5.000		0.040527	
	Carbon Black	1333-86-4	0.550		0.004458	
Solder Balls					0.004043	0.176%
	Tin (Sn)	7440-31-5	96.50		0.003902	
	Silver (Ag)	7440-22-4	3.00		0.000121	
	Copper (Cu)	7440-50-8	0.50		0.000020	

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Revision History

The following table shows the revision history for this document.

Date	Version	Description of Revisions
11/28/14	1.1	Initial Xilinx release.

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